



Material Content Data Sheet



Sales Product Name		BTT6050-2EKA		Issued		22. May 2015		
MA#		MA001369076						
Package		PG-DSO-14-40		Weight*		149.96 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.421	2.28	2.28	22813	22813
leadframe	inorganic material	phosphorus	7723-14-0	0.017	0.01		116	
	non noble metal	zinc	7440-66-6	0.070	0.05		464	
	non noble metal	iron	7439-89-6	1.392	0.93		9281	
wire	non noble metal	copper	7440-50-8	56.512	37.68	38.67	376838	386699
	non noble metal	copper	7440-50-8	1.065	0.71	0.71	7101	7101
	encapsulation	organic material	carbon black	1333-86-4	0.168	0.11		1117
	plastics	epoxy resin	-	7.708	5.14		51396	
	inorganic material	silicondioxide	60676-86-0	75.903	50.61	55.86	506144	558657
leadfinish	non noble metal	tin	7440-31-5	1.241	0.83	0.83	8278	8278
plating	noble metal	silver	7440-22-4	1.417	0.95	0.95	9452	9452
glue	plastics	epoxy resin	-	0.184	0.12		1225	
	noble metal	silver	7440-22-4	0.866	0.58	0.70	5775	7000
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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